Course Curriculum

for

Master of Technology Programme

in

Electronics and Communication Engineering Department



National Institute of Technology Goa

Farmagudi, Ponda, Goa - 403 401

Semester-wise Credit Distribution

Semester	Total Credits
I	19
II	17
III	14
IV	14
Total Credits	64

M.Tech. Program Name: VLSI

Semester-wise Distribution of the Courses

Semester I				
SI. No.	Course Code	Course Name	Total Credits (L-T-P)	Credits
1	EC600	Digital IC Design	(3-0-0)	3
2	EC601	Analog IC Design	(3-0-0)	3
3	EC602	Semiconductor Device Theory and Modelling	(3-0-0)	3
4	EC603	Digital Signal Processing	(3-0-0)	3
5	EC604	IC Design Laboratory	(0-0-6)	3
6	EC605	Semiconductor Device Simulation Laboratory	(0-0-3)	2
7	EC606	Seminar	(0-0-3)	2
Total Credits			19	

Semester II				
			Total Credits	Credits
SI. No.	Course Code	Course Name	(L-T-P)	
1	EC650	VLSI Testing and Testability	(3-0-0)	3
2	EC651	VLSI Technology	(3-0-0)	3
3		Elective I	(3-0-0)	3
4		Elective II	(3-0-0)	3
5	EC652	System Design Laboratory	(0-0-6)	3
6	EC653	VIVA-VOCE	-	2
7	HU650*	Communication Skills and Technical Writing	(1-0-2)	-
Total Credits			17	

Semester III				
			Total Credits	Credits
SI. No.	Course Code	Course Name	(L-T-P)	
1		Elective III	(3-0-0)	3
2		Elective IV	(3-0-0)	3
3	EC700	Major Project-I	(0-0-12)	8
Total Credits			14	

Semester IV				
			Total Credits	Credits
SI. No.	Course Code	Course Name	(L-T-P)	
1	EC750	Major Project-II	(0-0-21)	14
Total C	redits			14

List of Electives

Electiv	es			
SI.	Course Code	Course Name	Total Credits (L-T-P)	Credits
1	EC800	Optoelectronics and Photonics	(3-0-0)	3
2	EC801	Architectural Design of IC	(3-0-0)	3
4	EC802	Digital Design using FPGA	(3-0-0)	3
5	EC803	System on CHIP	(3-0-0)	3
6	EC804	Mixed Signal Design	(3-0-0)	3
7	EC805	VLSI Embedded Systems	(3-0-0)	3
8	EC806	VLSI Design Automation	(3-0-0)	3
9	EC807	Compound Semiconductor Devices	(3-0-0)	3
10	EC808	Nano-electronic Device Engineering	(3-0-0)	3
11	EC809	Active Filter Design	(3-0-0)	3
12	EC810	Low Power VLSI Design	(3-0-0)	3
13	EC811	Power Management IC's	(3-0-0)	3
14	EC812	Advanced Topics in VLSI	(3-0-0)	3
15	EC813	Memory Design & Testing	(3-0-0)	3
16	EC814	IC for Broadband communication	(3-0-0)	3
17	EC815	CMOS RF IC Design	(3-0-0)	3
18	EC816	Advanced Antenna Theory	(3-0-0)	3
19	EC817	VLSI Signal Processing	(3-0-0)	3
20	EC818	Multi-rate Signal Processing	(3-0-0)	3
21	EC819	Multimedia Systems	(3-0-0)	3
22	EC820	Selected Topics in ECE - I		1
23	EC821	Selected Topics in ECE - II		2
24	EC822	Selected Topics in ECE - III	(3-0-0)	3

Progra	m Electives			
SI.	Course Code	Course Name	Total Credits (L-T-P)	Credits
1	EC850	Data Structures and Algorithms	(3-0-0)	3
2	EC851	Advanced Computer Architecture	(3-0-0)	3
3	EC852	Optimization Techniques	(3-0-0)	3
4	EC853	Linear Algebra	(3-0-0)	3
5	EC854	Random Processes	(3-0-0)	3

Core Subject Syllabus

Subject Code	Digital IC Degion	Credits: 3(3-0-0)
EC600	Digital IC Design	Total hours: 42
Course Objectives	To understand the fundamental properties of digital Integrated	
	MOSFET equations and to develop skills for various logic circuits design styles. The course also involves analysis of performance me	•
Module 1	Implementation of strategies for digital ICs	10 hours
Custom Circuit design, Ce CMOs inverter, Power dis	ell based and Array based design implementations. Static and Dynam sipation, Logical effort.	nic Characteristics of
Module 2	Designing combinational and sequential circuits	14 hours
0	erent styles of logic circuits, Logical effort of complex gates, Static	•
1 1	es, Dynamic CMOS Logic. Timing metrics of sequential circuits, Dy	namic latches and
Registers. Pipelining. Module 3	Interconnect and Timing Issues	12 hours
	nd performance estimation - Resistance, Capacitance	
estimation - Switching characteristics of Clock Skew and Jitter.	aracteristics - Delay models –Timing issues in Digital circuits, Powe	r dissipation. Impact
Module 4	Memory Design	6 hours
Read-Only Memories, Recell, Sense amplifiers.	OM cells, Read-write memories (RAM), dynamic memory design,	6 transistor SRAM
Reference Books		

- 1. Jan M. Rabaey, Anantha Chandrakasan, and Borivoje Nikolic *Digital Integrated Circuits A design perspective*, Pearson, 2003.
- 2. M. Kang & Y. Leblebici, CMOS Digital Integrated Circuits, McGraw Hill, 1999.
- 3. John P. Uyemura, Introduction to VLSI Circuits, Wiley India Pvt. Ltd., 2012.
- 4. Eugene Fabricius, Introduction to VLSI Design, New Ed Edition, Tata McGraw Hill Education, 1990.
- 5. Material from the *Journal of Solid-state Circuits* and the *International Solid-state Circuits Conference* proceedings.

Subject Code EC601	Analog IC Design	Credits: 3(3-0-0) Total hours: 42	
Course Objectives	This course covers the analysis and design of analog integrated basic building blocks to different implementations of the technology.	· ·	
Module 1	CMOS amplifiers basics	12 hours	

Introduction to MOS Capacitances, passive components and their parasitics, small and large signal modelling and analysis. Different Single stage and Differential Amplifiers, Current Mirrors.

Module 2 Multi-stage amplifiers 12 hours

Telescopic and Folded cascode amplifiers, Slew-rate, Pole splitting, Two-stage amplifiers - analysis, Frequency response, Stability compensation, Common mode feedback analysis, feedback amplifier topologies.

Module 3 References 6 hours

Supply independent biasing, Bandgap reference, Constant-Gm biasing.

Module 4 Nonlinearity, Mismatch and Layout 10 hours

Noise: Types of Noise, noise model, Nonlinearity of Differential Circuits, Capacitor nonlinearity, Mismatch analysis, Offset cancellation techniques,

Layout Techniques

- 1. B. Razavi, Design of Analog CMOS Integrated Circuits, Mcgraw-Hill Education, 2002.
- 2. David Johns & Ken Martin, Analog Integrated Circuit Design, Wiley-India, 2008.
- 3. P. Allen & D. R. Holberg, CMOS Analog Circuit Design, Oxford Press, 2011.
- 4. P. Gray, P. Hurst, S. Lewis, R. Meyer, *Analysis and Design of Analog Integrated Circuits*, Wiley-India, 2008
- 5. Gregorian and Temes, Analog MOS Integrated Circuits for Signal Processing, Wiley-India, 2008.

Subject Code	Semiconductor Device Theory and	Credits: 3(3-0-0)	
EC602	Modelling	Total hours: 42	
Course Objectives	To familiarize with the physical concepts behind the operation devices and also covers high performance, high speed semicond VLSI systems.		
Module 1	Concentration and motion of carriers in Semiconductor bulk	8 hours	
Valence band and Energy band models of intrinsic and extrinsic semiconductors. Thermal equilibrium carrier			

concentration. Carrier transport phenomena, Recombination and generation.

Quantitative theory of PN junctions 10 hours Module 2

Band diagrams, electrostatics of a p-n junction diode, ideal static I-V characteristics and deviations including breakdown, ac small signal equivalent circuit, switching characteristics, Schottky junctions, Ohmic contacts.

Module 3	BJT	10 hours
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Bipolar device Design and Modeling, Small and large signal models, Non-ideal effects, breakdown voltage, charge storage, Multidimensional effects, Bipolar Device optimization & performance factors for digital and analog circuits, Brief overview of BJT CAD SPICE model and VBIC model introduction.

Module 4	MOSFET Alternate MOS structures	14 hours

Analysis of MOSFET, Calculation of threshold voltage. Static I-V characteristics of MOSFETs, MOSFET capacitances, C-V characteristics, Channel length modulation, body bias effect and short channel effects, MOS switch, MOSFET models for calculation, Alternate MOS structures (SOI devices and Multi-gate MOSFETs) in brief.

- 1. M. S. Tyagi, Introduction to Semiconductor materials and Devices, John Wiley & Sons, 1991.
- 2. S. M. Sze, Modern Semiconductor Device Physics, Wiley, 1998.
- 3. Yuan Taur & Tak H Ning, Fundamentals of Modern VLSI Devices, Cambridge University Press, 1998.
- 4. Ben G. Streetman, Solid State Electronic Devices, Prentice Hall, Fifth Edition, 2000.
- 5. J. P. Colinge, FinFETs and other multigate transistors, Springer, 2007.

Subject Code	D': '4 .1 C' 1 D	Credits: 3(3-0-0)
EC603	Digital Signal Processing	
Course Objectives	To expose to the basic concepts in digital processing system des	ign with emphasis on
	the digital filter design and related algorithmic and implementation	n issues. Specifically,
	focus will be on FIR, IIR Filters classical and optimized designation	gn techniques, issues
	related to finite word length and advantage of specific structure	s for implementation.
	Various specific digital filters will be discussed and their use for se	ome signal processing
	applications will be also discussed.	
Module 1	Review of Signals and Systems	8 hours
Introduction to CT signals and systems, DT signals and systems, Frequency analysis of signals, Transform domain analysis of LTI systems, DFT- Properties, FFT algorithms.		
Module 2	Design of Digital Filters	12 hours
Digital filter structures, II	R Digital filter design and implementation, FIR digital filter design	and implementation,
Digital filter applications, Optimization Techniques in Filter Design.		
Module 3	Finite Word length problems in Digital Filters	12 hours
Representation of binary	numbers in digital filters, Fixed and Floating point represer	ntation, Error due to
	quantization, truncation and round off, Implementation of different structures, Issues associated with IIR filters.	
Module 4	Introduction to Multi-rate Signal Processing	10 hours
	Sampling rate conversion, Decimation by an integer factor, Interpolation by an integer factor, Sampling rate	
conversion by a rational factor, Sampling rate converter as a time variant system, Practical structures for		
decimators and interpolators. Multi stage implantation of digital filters.		

- 1. John G. Proakis, and Dimitris G. Manolakis, *Digital Signal Processing Principles, Algorithms and Applications*, Pearson, 2002.
- 2. P.S.R. Diniz, E. A. B. da Silva, and S. L. Netto, *Digital Signal Processing System Analysis and Design*, Cambridge, 2010.
- 3. Sanjit K. Mitra, Digital Signal Processing A Computer-Based Approach, McGraw Hill, 2003.
- 4. Vinay K. Ingle and John G. Proakis, *Essential of Digital Signal Processing using MATLAB*, Cengage Learning, 2012.
- 5. P. P. Vaidyanathan, Multirate Systems and Filter Banks, Pearson-Education, Delhi, 2004.
- 6. N. J. Fliege N J, Multirate Digital Signal Processing, John Wiley and sons, 1994.

Subject Code	IC Design Laboratory	Credits:3 (0-0-6)
EC604		Total hours: 84
Course Objectives	This course introduces CMOS schematic design, layout technique tools, netlist synthesis, place & route and timing verification. introduced in this course.	_
Module 1	Digital IC design	

Schematic simulation of CMOS Inverter, power and delay issues and Layout techniques. Pre layout simulation, Parasitic extraction, Post layout simulation.

Design of Adders, Multiplier and Shifters, Synthesis with timing constraints, Pre layout simulation, Floor planning, Placement, Routing, Parasitic extraction, Post layout simulation.

Standard cell layout techniques.

Module 2 Analog IC design

Single stage amplifiers: Completer characterization of Common source amplifier, Common drain amplifiers, Common Gate amplifiers, Cascode amplifiers.

Differential amplifiers: Completer characterization of Single stage differential amplifiers, Folded Cascode, Telescopic amplifiers

Two-stage amplifiers. Layout techniques

- 1. James R.Armstrong, F.Gail Gray, *VHDL Design Representation and Synthesis*, Pearson Education, 2007.
- 2. Jan M Rabaey, *Digital Integrated Circuits A Design Perspective*, Prentice Hall, Second Edition, 2005.
- 3. Naveed A. Sherwani, Algorithms for VLSI Physical Design Automation, Springer, Third Edition, 1999.
- 4. B. Razavi, Design of Analog CMOS Integrated Circuits, McGraw-Hill Education, 2002.
- 5. Allan Hastings, *The Art of Analog Layout*, Prentice Hall, Second Edition, 2005.

Subject Code	Semiconductor Device Simulation	Credits: 2 (0-0-3)
EC605	Laboratory	Total hours: 42
Course Objectives	This course covers the analysis and design of pn diode, BJT, device structures.	MOSFET and novel
Module 1	2D simulations	

Use device simulator to generate a pn diode structure. Simulate I-V characteristics and also get the C-V characteristics. Find the carrier concentration, electron and hole concentration, electric field, potential distribution (at different biases) and doping distribution across the structure. Check the current and capacitance values with hand calculations. Extract Vbi from capacitance characteristics. Freeze different models one used. Process simulates the same structure with same/similar doping levels. Exporting the process simulated structure in to device simulator, extract I-V and C-V characteristics and make similar observations as in device simulation and explain the differences if any.

mulations

Bipolar devices are integral part of high speed circuit. Any given MOSFET has a parasitic BJT. If not taken care in device design, the parasitic BJT may lead to very different behavior. The aim of these experiments is to understand the different effects in BJT. For a lateral/planar BJT, the following experiments can be performed:

- 1) Variation in α , β dc and γ with base doping and base width and respective current characteristics
- 2) Variation in α , β dc and γ with emitter width and respective current characteristics

Module 3 3D MOS device

Simulate a 3D MOS device (FINFET/SOI/Piller MOSFET, Tri-gate MOSFET GAA MOSFET) and obtain their characteristics.

- 1. User Manuals of respective software.
- 2. Jean- Pierrie Colinge, Silicon-on-insulator Technology: Materials to VLSI, Springer, Second Edition, 1997.
- 3. M.S. Tyagi, Introduction to Semiconductor materials and Devices, John Wiley & Sons, 1991.
- 4. J. P. Colinge, FinFETs and other multigate transistors, Springer, 2007.

Subject Code EC650	VLSI Testing and Testability	Credits: 3 (3-0-0) Total hours: 42
Course Objectives	This course covers introduction to the concepts and techniques of VLSI (Very Large Scale Integration) design verification and testing. Details of test economy, fault modeling and simulation, defects, Automatic Test Pattern Generation (ATPG), design for testability, and built-in self-test (BIST) also covered.	
Module 1	Fundamental of VLSI testing	12 hours

Basic of VLSI testing, Scope of testing and verification in VLSI design process, Issues in test and verification of complex chips, embedded cores and SOCs.

Module 2 Fault Modeling and testing 12 hours

Fault models, fault detection and redundancy, fault equivalence and fault location, fault dominance, automatic test pattern generation, Design for testability, Scan design, Test interface and boundary scan. System testing and test for SOCs. Delay fault testing.

Module 3 Test automation and Design verification 10 hours

BIST for testing of logic and memories, Test automation, Design verification techniques based on simulation, analytical and formal approaches.

Module 4Functional and Timing verification8 hours

Functional verification, Timing verification, Formal verification, Basics of equivalence checking and model checking, Hardware emulation.

- 1. M. Abramovici, M. A. Breuer and A. D. Friedman, *Digital Systems Testing and Testable Design*, Jaico Publishing House, 1990.
- 2. T. Kropf, Introduction to Formal Hardware Verification, Springer Verlag, 2000.
- 3. Neil H. E. Weste and Kamran Eshraghian, *Principles of CMOS VLSI Design*, Addison Wesley, Second Edition, 1993.
- 4. Neil H. E. Weste and David Harris, *Principles of CMOS VLSI Design*, Addison Wesley, Third Edition, 2004
- 5. M. Bushnell and V. D. Agrawal, *Essentials of Electronic Testing for Digital, Memory and Mixed-Signal VLSI Circuits*, Kluwer Academic Publishers, 2000.

Subject Code	VLSI Technology	Credits: 3 (3-0-0)
EC651	, Est reciniology	Total hours: 42
Course Objectives	This course aims at understanding the manufacturing methods	and their underlying
	scientific principles in the context of technologies used in VLSI ch	ip fabrication.
Module 1	Crystal Growth, Wafer manufacturing and Clean rooms	12 hours
CMOS Process flow starting from Substrate selection to multilevel metal formation, comparison between bulk and SOI CMOS technologies. Crystal structure, Czochralski and FZ growth methods, Wafer preparation and specifications, SOI Wafer manufacturing.		
Clean rooms, wafer cleaning and gettering : Basic concepts, manufacturing methods and equipment, Measurement methods.		

Module 2Photolithography and Oxidation10 hours

Photolithography: Light sources, Wafer exposure systems, Photoresists, Baking and development, Mask making, Measurement of mask features and defects, resist patterns and etched features.

Oxidation: Wet and Dry oxidation, growth kinetics and models, defects, measurement methods and characterization.

Module 3 Diffusion and Ion-implantation 8 hours

Diffusion: Models for diffused layers, Characterization methods, Segregation, Interfacial dopant pileup, oxidation enhanced diffusion, dopant-defect interaction.

Ion-implantation: Basic concepts, High energy and ultralow energy implantation, shallow junction formation & modeling, Electronic stopping, Damage production and annealing, RTA Process & dopant activation

Module 4	Thin film Deposition, Etching Technologies and Back-end	12 hours
	Technology	

Thinfilm Deposition: Chemical and physical vapour deposition, epitaxial growth, manufacturing methods and systems, deposition of dielectrics and metals commonly used in VLSI, Modeling deposition processes.

Etching Technologies: Wet etching, Plasma etching, RIE, Etching of materials used in VLSI, Modeling of etching. **Back-end Technology:** Contacts, Vias, Multi-level Interconnects, Silicided gates and S/D regions, Reflow & planarization, Multi-chip modules and packaging.

- 1. James Plummer, M. Deal and P.Griffin, Silicon VLSI Technology, Prentice Hall Electronics, 2000.
- 2. Stephen Campbell, The Science and Engineering of Microelectronics, Oxford University Press, 1996.
- 3. S. M. Sze (Ed), VLSI Technology, McGraw Hill, Second Edition, 1988.
- 4. S.K. Ghandhi, VLSI Fabrication Principles, John Wiley Inc., New York, 1983.
- 5. C.Y. Chang and S. M. Sze (Ed), *ULSI Technology*, McGraw Hill Companies Inc, 1996.

Subject Code	Cristone Dogian I about our	Credits:3 (0-0-6)
EC652 System Design Laboratory	System Design Laboratory	Total hours: 84
Course Objectives	This course covers the Laboratory topics based on the core and elective subjects	
	Example syllabus based on electives like System on chip or CN	MOS RF IC is given
	below.	
	 a) System on chip lab course introduces CAD tool for system design implementation of Prototype SoC platform using FPGA and ARM process boards. Xilinx ISE, EDK and ARM tool-chain will be used in this course. b) The objective of this course is to cover the design issue related to RF Design. 	
Module 1	System on chip	

Development of embedded systems in both ARM and FPGA platforms. Examples on multiprocessor environments. Application case studies of signal processing applications FFT, FIR, DCT, JPEG, H.264 etc. Custom IP interfacing techniques for different protocols for above applications. Embedded OS development on FPGA/ARM platforms and device driver development.

Mini Project

Module 2	RF IC Design	
Characterization of a MO	S transister for DE Design of a tuned LNA and performance analy	rais Design of a VC

Characterization of a MOS transistor for RF, Design of a tuned LNA and performance analysis, Design of a VCO and performance analysis, Design of a mixer based on a Gilbert cell.

Mini Lab Projects

- 1. Doug Amos, Austin Lesea and Rene Richter, FPGA-Based Prototyping Methodology Manual Best Practices in Design-for-Prototyping, Synopsys, Inc, Mountain View, 2010.
- 2. Ron Sass and Andrew G. Schmidt, *Embedded Systems Design with Platform FPGAs Principles and Practices*, Elsevier Inc, 2010.
- 3. J. Staunstrup and W. Wolf, *Data books of ARM7/ARM9*, *Hardware/Software Co-Design: Principles and Practice*, Kluwer Academic Publishers, 1997.
- 4. Silage, Dennis, Embedded Design Using Programmable Gate Arrays, Book stand Publishing, 2008.
- 5. K.V.K.K. Prasad, *Embedded Real Time Systems: Concepts, Design & Programming*, Dreamtech Publication, 2003.
- 6. G. DeMicheli, R. Ernst, and W. Wolf, *Readings in Hardware/Software Co-Design*, Academic Press, 2002.
- 7. User manual of the tools for RF IC design.
- 8. Razavi, B., RF microelectronics, 2nd ed. int. Pearson Education International, 2012.
- 9. Lee, T.H., *The design of CMOS radio-frequency integrated circuits*. 2nd ed. Cambridge University Press, 2004.

Subject Code	Seminar	Credits: 2 (0-0-3)
EC606		
Course Objectives	Students will have to choose a topic in current VLSI related areas or industry practices and prepare a write up along with suitable presentation and demonstration.	

Subject Code	VIVA-VOCE	Credits: 2
EC653		
Course Objectives	Students will have to attend for a viva-voce in front of all the faculty of the department for the evaluation of the subjects studied in the first year (I and II semesters) with a suitable demonstration.	

Subject Code	Communication Skills and Technical	Credits: 0 (1-0-2)	
HU650* (Audit Course)	Writing	Total hours: 45	
Course Objectives	This course is meant for developing Professional Communic Writing Skills among the students. The Lab hours will give en Presentation and Seminar (on different emerging topics) followed and discussion.	nphasis on Technical	
Module 1		12 hours	
Introduction to Comm	nunication-Definition-Types-Classifications, Writing Exercises	-Paragraph- Précis-	
Summary/Executive Summary/Abstract			
Module 2		8 hours	
Technical Reports-Types-Format-Nuances to be followed			
Module 3		10 hours	
Preparation of Technical	Document-Reports-Instruction Manuals-Project Proposal (Prefato	ory Part- Main Part-	
Terminal Section)			
Module 4		15 hours	
Presentation of Technical	Presentation of Technical Report (Kinesics, Proxemics, and Professional Ethics)		

- 1. Raman and Sharma, Communication Skills, OUP, 2011.
- 2. Mandel, Steve, *Technical Presentation Skills: A Practical Guide for Better Speaking* (Revised Edition), Crisp Learning, 2000.
- 3. Wood, Millett, The Art of Speaking, Drake Publishers, 1971.
- 4. Lencioni, Patrick, *The Five Dysfunctions of a Team*, John Wiley and Sons, 2006.

Subject Code EC800	Optoelectronics and Photonics	Credits: 3(3-0-0) Total hours: 42
Course Objectives	This course will cover basic laser theory, semiconductor physics, optical properties of semiconductors and quantum wells, optical detection and noises, electromagnetic waves. The primary emphasis will be on semiconductor materials and devices.	
Module 1	Semiconductor lasers	10 hours

Semiconductor lasers for optical fiber communications, Fabry-Perot cavity, heterostructure semiconductor lasers, single frequency semiconductor lasers, semiconductor lasers for coherent systems. Distributed feedback in Ga-As-P lasers.

Module 2	Photo detectors and Optical Receiver Operation	12 hours

Device structure and fabrication, photo-detectors for fiber optics, reverse bias photo-detectors, dark current, quantum efficiency, signal to notice ratio, types of detectors. Receivers for digital fiber optic communication systems: basic components, detectors for digital fiber optic receivers, PIN diode, Avalanche photodiode, Fronts ends for digital fiber optic receivers, equalizer for optical communication, receivers, PIN-FET receivers for longer wavelength communication systems.

Module 3	Transmission System	12 hours

Coherent optical fiber transmission systems, coherent detection principles, comparison of direct and coherent performance, homodyne and heterodyne systems. Nonlinear process in optical fibers, phase matching in waveguide, phase matched harmonic generation in waveguides. Second harmonic generation (SHG) in integrated optics, Cerenkov configuration SHG.

Module 4	Sensor and Devices	8 hours
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Optical fiber sensor and devices, intensity modulation through light interruption, distributed sensing with fiber optics. Basic principles of interferometric optical fiber sensor, signal processing in mono mode fiber optic sensor, photonic band gap materials.

- 1. G. Keiser, Optical fiber communication, McGraw-Hill, 2008.
- 2. J. Seniar, Optical fiber Communication, Prentice-Hall International, 1985.
- 3. A. K. Ghatak, *Introduction to optical fiber*, Cambridge University Press, 1998.
- 4. Max Born & Emil Wolf, *Principles of Optics*, Cambridge University Press, 1999.
- 5. Saleh & Teich, Fundamentals of Photonics, Wiley-Interscience, 2007.

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Architectural Design of ICs	Total hours: 42
This course covers algorithm, architecture and circuit design trade power, performance and area.	e-offs to optimize for
	12 hours
	This course covers algorithm, architecture and circuit design trade

VLSI Design flow, general design methodologies, Mapping algorithms into Architectures: Signal flow graph, data dependences, data-path synthesis, control structures, critical path and worst case timing analysis, concept of hierarchical system design; Data-path element: Data-path design philosophies, fast adder, multiplier, driver etc.

Module 2 12 hours

Data-path optimization, application specific combinatorial and sequential circuit design, CORDIC unit; Pipeline and parallel architectures: Architecture for real time systems, latency and throughput related issues, clocking strategy, power conscious structures, array architectures; Control strategies: Hardware implementation of various control structures, micro-programmed control techniques, VLIW architecture

Module 3 10 hours

Testable architecture: Controllability and observability, boundary scan and other such techniques, identifying fault locations, self-reconfigurable fault tolerant structures.

Module 4 8 hours

Trade-off issues: Optimization with regard to speed, area and power, asynchronous and low power system design, ASIC (application specific integrated circuits) and ASISP (application specific instruction set processors) design

- 1. U. Meyer-Baese, *Digital Signal Processing with Field Programmable Gate Arrays*, Springer-Verlag, 2001.
- 2. S. Y. Kung, VLSI Array Processors. Prentice, Prentice-Hall, 1988.
- 3. K. Parhi, VLSI Digital Signal Processing Systems, Wiley & Sons, 1999.
- 4. J. Rabaey, A. Chandrakasan and B. Nikolic, *Digital Integrated Circuits: A Design Perspective*, Prentice Hall, Second Edition, 2003.

Subject Code		Credits: 3(3-0-0)
EC802	Digital Design using FPGAs	Total hours: 42
Course Objectives	To learn field programmable gate array (FPGA) technologies and utilize associated computer aided design (CAD) tools. To synthesize digital systems with testing strategies and construct test benches.	
Module 1	Introduction	08 hours

Digital system design options and trade-offs, Design methodology and technology overview, High Level System Architecture and Specification: Behavioural modelling and simulation.

Module 2 Tool for logic Implementation 12 hours

Hardware description languages, combinational and sequential design, state machine design, synthesis issues, test benches.

Overview of FPGA architectures and technologies: FPGA Architectural options, granularity of function and wiring resources, coarse vs fine grained, vendor specific issues (emphasis on Xilinx / Altera).

Module 3 Implementation on FPGA 12 hours

Logic block architecture: FPGA logic cells, timing models, power dissipation I/O block architecture: Input and Output cell characteristics, clock input, Timing, Power dissipation, Programmable interconnect - Partitioning and Placement, Routing resources, delays.

Module 4 Applications 10 hours

Applications - Embedded system design using FPGAs, DSP using FPGAs, Dynamic architecture using FPGAs, reconfigurable systems, application case studies. Simulation / implementation exercises of combinational, sequential and DSP kernels on Xilinx / Altera boards.

- 1. M. J. S. Smith, *Application Specific Integrated Circuits*, Pearson, 2000.
- 2. Peter Ashenden, Digital Design using Verilog, Elsevier, 2007.
- 3. W. Wolf, FPGA based system design, Pearson, 2004.
- 4. Clive Maxfield, *The Design Warriors's Guide to FPGAs*, Elsevier, 2004.

Subject Code EC803	System on Chip Design	Credits: 3(3-0-0) Total hours: 42
Course Objectives	This course covers SoC design and modeling techniques with emphasis on architectural exploration, assertion-driven design and the concurrent development of hardware and embedded software.	
Module 1	Low-level modeling and design refactoring	12 hours

Verilog RTL Design with examples. Simulation styles (fluid flow versus eventing). Basic RTL to gates synthesis algorithm. Using signals, variables and transactions for component inter-communication. SystemC overview. Structural hazards, retiming, refactoring.

Module 2 Design partition, high-level and hybrid modeling 12 hours

Bus and cache structures, DRAM interface. SoC parts. Design exploration. Hardware/software interfaces and codesign. Memory maps. Programmer's model. Firmware development. Transactional modeling. Electronic systems level (ESL). IP-XACT. Instruction set simulators, cache modeling and hybrid models.

Module 3 Assertions for design, testing and synthesis 10 hours

Assertion based design: testing and synthesis. PSL/SVA assertions. Temporal logic compilation to FSM. Glue logic synthesis. Combinational and sequential equivalence. High-level Synthesis and Automated Assembly.

Module 4 Power control and power modeling 8 hours

Power consumption formulae. Pre-layout wiring estimates. Clock gating. Frequency and voltage dynamic scaling.

- 1. Lin, Y-L.S. Essential issues in SOC design: designing complex systems-on-chip, Springer, 2006.
- 2. Grotker, T., Liao, S., Martin, G. & Swan, S. System design with SystemC, Springer, 2002.
- 3. Ghenassia, F. *Transaction-level modeling with SystemC: TLM concepts and applications for embedded systems*, Springer, 2010.
- 4. D. Gajski, S. Abdi, A. Gerstlauer, G. Schirner, *Embedded System Design: Modeling, Synthesis, Verification*, Springer, 2009.
- 5. G. De Micheli, Synthesis and Optimization of Digital Circuits, McGraw-Hill, 1994.

Subject Code EC804	Mixed Signal Design	Credits: 3(3-0-0) Total hours: 42
Course Objectives	This course covers theory and concepts to Integrate both Analog and Digital subsystems on a single monolithic chip to create an electronic system. The syllabus includes primitive cells, biasing and references, op-amp designs, switched capacitor A/D and D/A converters, and clock generation systems for digital and mixed signal.	
Module 1	Filter basics	10 hours

Analog continuous-time filters: passive and active filters, Basics of analog discrete-time filters and Z-transform, Sample and Hold Circuits, Switched-capacitor filter architectures.

Module 2 ADC and DAC 12 hours

Basics ADC, Successive approximation ADCs, Flash ADC, folding-and-interpolation ADC, Pipeline ADC, Introduction/Characterization of DACs, various architectures of high speed DAC

Module 3 Over sampled ADC 10 hours

Over sampled ADC: Working principle and architecture of a Sigma-delta ADC, multistage sigma-delta converters, Design of decimation filter.

Module 4Advanced Topics10 hours

VCO, Loop Filter, Charge pump, Precautionary measures for integrating analog and digital modules within an IC, floor planning and physical design of mixed signal IC design.

- 1. B. Razavi, Design of Analog CMOS Integrated Circuits, McGraw-Hill Education, 2002.
- 2. David Johns & Ken Martin, Analog Integrated Circuit Design, Wiley-India, 2008.
- 3. P. Allen & D. R. Holberg, CMOS Analog Circuit Design, Oxford Press, 2011.
- 4. B. Razavi, Principles of Data Conversion System Design, IEEE Press, 1995.
- 5. Schreier & Temes, Understanding Delta-Sigma Data Converters, Wiley-IEEE Press, 2004.
- 6. Franco Maloberti, Data Converters, Springer-2007.
- 7. Jacob Baker, CMOS Mixed Signal Circuit Design, Wiley-IEEE Press, Second Edition, 2009.

Subject Code EC805	VLSI & Embedded systems	Credits: 3(3-0-0) Total hours: 42
Course Objectives	The course covers prototype development of embedded VLSI system. The course focuses on software application by mapping of functions onto hardware components. In addition to the conceptual foundations, this course also covers various design methodologies and platforms based on ARM and FPGA.	
Module 1	Embedded System on chip platforms	5 hours

Introduction to embedded system and design methodology for ARM and FPGA devices, Prototype development of embedded application advantages, design challenges, Differences between General Purpose Processor, Digital signal Processor, ASIC and FPGA based System On Chip.

Module 2 MPSoC platform for FPGAs and ARM 25 hours

Embedded Computer Organization, emphasis on different embedded processors and multiprocessor and architectures. Application profiling, Hardware-software co-design, Simple & Autonomous I/O Controllers, Custom IP (Intellectual-Property) hardware design for System-On-a-Chip; Design of Master and Slave Bus protocols based IPs, Bus protocols (AXI, PLB, FSL, NPI etc.). Concepts & types of Memory and interfacing, Cache Memory, Cache mapping techniques and impact on system performance, Design Metrics, General purpose peripherals (interrupt, timer, clock, DMA etc.) and special purpose peripherals Serial Transmission techniques & Standards, Wireless protocols, and advanced high speed buses.

Module 3	Analysis and case-studies	12 hours

Architecture exploration of IP, System Level Design Trade-offs, Power, Energy, Performance and Area. Frequency, memory and power, Productivity, Reusability, Clocking and Synchronisation issues, Co-simulation using different simulators, system level optimization, Design for Test, Advanced design Methodologies using HLS for an application like JPEG 2000, MJPEG, H.264, Embedded operating systems for SoC platforms.

- 1. Ron Sass and Andrew G. Schmidt, *Embedded Systems Design with Platform FPGAs Principles and Practices*, Elsevier Inc, 2010.
- 2. Doug Amos, Austin Lesea and Rene Richter, FPGA-Based Prototyping Methodology Manual Best Practices in Design-for-Prototyping, Synopsys, Inc, Mountain View, 2010.
- 3. Embedded System Design: A unified Hardware/Software Introduction, Frank Vahid, and Tony Givargis.
- 4. Lin, Y.L.S., Essential issues in SOC design: designing complex systems-on-chip, Springer, 2006.
- 5. Sloss, Andrew, Dominic Symes, and Chris Wright, ARM system developer's guide: designing and optimizing system software. Morgan Kaufmann, 2004.
- 6. G. DeMicheli, R. Ernst, and W. Wolf, *Readings in Hardware/Software Co-Design*, Academic Press, 2002.
- 7. Peter J. Ashenden, *Digital Design: An Embedded Systems Approach Using Verilog*, Morgan Kaufmann Publication, 2008.

Subject Code EC806	VLSI Design Automation	Credits: 3 (3-0-0) Total hours: 42
Course Objectives	The objective of physical design automation is to carry out mapping of the given structural representation into layout representation optimally using computers so that the resulting layout satisfies topological, geometric, timing and power-consumption constraints of the design.	
Module 1	VLSI CAD basics	12 hours

VLSI CAD Flow, Chip Layout styles, High-level synthesis, Algorithm Design Approaches for VLSI CAD, models for physical design, Graph theory fundamentals.

Module 2	Partitioning and Routing	12 hours
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Partitioning, Floorplanning-tutte's approach, Graph-theoretic models of floorplans, Placement-general problem, quality metrics, Gordian, Design Rule Check, Compaction, Clock and Power Routing—Global routing, Channel routing.

Module 3 Optimization and Synthesis 10 hours

Optimization techniques, Logic synthesis and Technology Mapping-Dynamic Programming, Dagon, VLSI and Circuit Design Issues including power and delay analysis.

Module 4	New topics in VLSI CAD	8 hours

Design consideration for Analog and Mixed Signal Design. Emerging topics in the VLSI CAD.

- 1. S. M. Sait, and H. Youssef, *VLSI Physical Design Automation: Theory and Practice*, World Scientific, 1999
- 2. T. H. Cormen, C. E. Leiserson, R. L. Rivest, and C. Stein, *Introduction to Algorithms*, MIT Press, Third Edition, 2009.
- 3. C. J. Alpert, D. P. Mehta, S. S. Sapatnekar, *Handbook of Algorithms for Physical Design Automation*, Auerbach Publications, 2008.
- 4. Sung Kyu Lim, Practical Problems in VLSI Physical Design Automation, Springer, 2008.
- 5. Naveed A Sherwani, Algorithms for VLSI Physical Design Automation, Third Edition, 1998.

Subject Code EC807	Compound Semiconductor Devices	Credits: 3 (3-0-0) Total hours: 42
Course Objectives	The goal of this course is to impart the elements of III-V compound semiconduc materials and their related electronic and photonic devices.	
Module 1	Introduction to compound semiconductor	12 hours

Compound semiconductor crystals, structural, optical properties and electrical properties, free carrier concentration and Fermi-Dirac integral, III-V alloys, Fermi level pinning, theories of barrier formation and of current flow, diffusive vs. ballistic flow; contrasts with p-n diodes.

Module 2Heterostructures12 hours

E-x Profiles, modulation doping. Conduction parallel to heterojunction; mobility in semiconductors and carrier scattering mechanisms, Conduction normal to junction: I-V models and characteristics.

Module 3 MESFETs 10 hours

Basic concept, models for terminal characteristics; accounting for velocity saturation. Dynamic models: large signal switching transients; small signal, high f models. Fabrication sequences; application-specific designs, examples of fabrication sequences.

Module 4 HFETs & HBTs 8 hours

Basic device, theory, Deep level problem, non-ideal behaviour, pseudomorphic solution, RF characteristics,.

- 1. M. S. Shur, M. S, *Physics of Semiconductor Devices*, Prentice-Hall, 1990.
- 2. Adachi, Sadao, *Physical Properties of III-V Semiconductor Compounds: InP, InAs, GaAs, GaP, InGaAs, and InGaAsP*, John Wiley & Sons, 1992.
- 3. S. M. Sze, High Speed Semiconductor Devices, Wiley, 1990.
- 4. S. M. Sze, *Physics of Semiconductor Devices*, Wiley, Second Edition, 1981.

Subject Code		Credits: 3(3-0-0)
EC808	Nano-Electronic Device Engineering	Total hours: 42
Course Objectives	This course will introduce the rapidly developing field of nano-engineering materials	
	and various device structures with special focus on their electronic properties.	
Module 1	Device Physics and Introduction to scaling issues	12 hours

Challenges going to sub-100 nm MOSFETs – fundamental limits for MOS operation, SCEs and DIBL effects, sub-threshold current, velocity saturation, Oxide layer thickness, tunneling, High-K gate dielectrics, effects of high-K gate dielectrics on MOSFET performance, power density, non-uniform dopant concentration, interconnect and lithography issues.

Module 2 Novel Device Structures

Novel MOS-based devices – Multiple gate MOSFETs, Silicon-on-nothing, Silicon-on-insulator devices, FD SOI, PD SOI, FinFETs, vertical MOSFETs, strained Si devices. SiGe HBTs.

Module 3 Hetero structure based devices 10 hours

Hetero structure based devices – Type I, II and III Heterojunction, Si-Ge heterostructure, hetero structures of III-V and II-VI compounds - resonant tunneling devices, MODFET/HEMT, Carbon nanotubes based devices – CNFET, characteristics, Spin-based devices – spinFET, characteristics.

Module 4 Quantum Effects 8 hours

Quantum structures – quantum wells, quantum wires and quantum dots, Single electron devices – charge quantization, energy quantization, Coulomb blockade, Coulomb staircase, Bloch oscillations

Reference Books

- 1. Mircea Dragoman and Daniela Dragoman, *Nanoelectronics Principles & devices*, Artech House Publishers, 2005.
- 2. Karl Goser, Nanoelectronics and Nanosystems: *From Transistors to Molecular and Quantum Devices*, Springer 2005.
- 3. Mark Lundstrom and Jing Guo, *Nanoscale Transistors: Device Physics, Modeling and Simulation*, Springer, 2005.
- 4. Vladimir V Mitin, Viatcheslav A Kochelap and Michael A Stroscio, *Quantum heterostructures*, Cambridge University Press, 1999.
- 5. S. M. Sze (Ed), High speed semiconductor devices, Wiley, 1990.
- 6. H.R. Huff and D.C. Gilmer, *High Dielectric Constant Materials for VLSI MOSFET Applications*, Springer 2005.
- 7. B. R. Nag, *Physics of Quantum Well Devices*, Springer 2002.
- 8. E. Kasper, D. J. Paul, Silicon Quantum Integrated Circuits Silicon-Germanium Heterostructures Devices: Basics and Realisations, Springer, 2005.

12 hours

Subject Code	A ative Filter Design	Credits: 3(3-0-0)	
EC809	Active Filter Design	Total hours: 42	
Course Objectives	To understand the fundamental concepts involved in the desig	n of Continuous-time	
	filters. To develop the skills required to design and verify the	various filter circuits	
	using op-amps and OTA's.		
Module 1	Filter Fundamentals	10 hours	
Filter Characterization, (Continuous-Time Filter Functions, Steps in Filter design, Butter	worth, Chebyshev &	
Inverse-Chebyshev filter i	response and pole locations. The Approximation Problem.		
Module 2	Ladder filter structures	10 hours	
LC ladder filter - prototyp	be & synthesis; Frequency transformation of low-pass filter. Active	elements, Impedance	
converters, Characteristics	s of IC op-amps, The Ideal Operational Transconductance Amplifie	r (OTA).	
Module 3	Realizations of active filters	12 hours	
Active-RC filters, Gm-C filters- Elementary Transconductance Building blocks, off-set problems, Limitations of opamp based filters. Characterization of on-chip integrated continuous time filters.			
Module 4	Switched capacitor circuits	10 hours	
Switched capacitor filters- First-order building blocks- Second order sections.			

- 1. R. Schaumann and M.E. Van Valkenburg, *Design of Analog Filters*, Oxford University Press, 2003.
- 2. P. V. Ananda Mohan, Current-Mode VLSI Analog Filters Design and Applications, Birkhauser, 2003.
- 3. Gobind Daryanani, Properties of Active networks synthesis and Design, Wiley, First Edition, 1976.
- 4. M.E. Van Valkenburg, *Analog Filter Design*, Oxford University Press, 1995.
- 5. T. Deliyannis, Y. Sun and J. K. Fidler, *Continuous-Time Active Filter Design*, CRC Press, 1998.
- 6. Material from the Journal of Solid-state Circuits and the International Solid-state Circuits Conference proceedings.

Subject Code	I D MICID:	Credits: 3 (3-0-0)
EC810	Low-Power VLSI Design	Total hours: 42
Course Objectives	To understand the critical requirements and implementation	
	circuits. The course also covers critical issue related to c	continued scaling of
	microelectronic circuits.	
Module 1	Introduction	08 hours
Introduction: Need for low power VLSI chips, Sources of power dissipation on Digital Integrated circuits,		
Emerging Low power approaches. Device & Technology Impact on Low Power: short circuit and leakage in		
CMOS Dynamia discination in CMOS		

CMOS, Dynamic dissipation in CMOS.

Module 2 **Low-Voltage CMOS Circuits** 10 hours

Introduction, Design style, Leakage current in Deep sub-micron transistors, device design issues, minimizing short channel effect, Low voltage design techniques using reverse Vgs, steep sub threshold swing and multiple threshold voltages, Testing with elevated intrinsic leakage, multiple supply voltages.

Module 3 **Circuit and logics** 12 hours

Low Power Circuits: Transistor and gate sizing, network restructuring and Reorganization, Special Flip Flops & Latches design, Low power digital cells library.

Logic level- Gate reorganization, signal gating, logic encoding, state machine encoding, pre-computation logic.

Module 4 **Architecture and system** 12 hours

Low power Architecture & Systems: Power & performance management, switching activity reduction, parallel architecture with voltage reduction, flow graph transformation, low power arithmetic components. Adiabatic Computation, Pass Transistor Logic Synthesis.

- 1. Gary K. Yeap, Practical Low Power Digital VLSI Design, KAP, 2002
- 2. Kaushik Roy, and Sharat Prasad, Low-Power CMOS VLSI Circuit Design, Wiley, 2000.
- 3. Anantha P. Chandrakasan, and Robert W. Brodersen, Low Power Digital CMOS Design, Kluwer Academic Publications, 1995.
- 4. Rabaey, and Pedram, Low Power Design Methodologies, Kluwer Academic, 1997
- 5. Philip Allen, and Douglas Holberg, CMOS Analog Circuit Design, Oxford University Press, 2002.

Subject Code	Dawan Managamant ICg	Credits: 3(3-0-0)	
EC811	Power Management ICs	Total hours: 42	
Course Objectives	This course covers operation principles of different dc-dc converters: switched-mode power converters, switched-capacitor power converters and linear regulators. Design and analysis of voltage references are also covered.		
Module 1		12 hours	
Synchronous Buck converter, Boost converter, Cuk Converter, dc-ac inverters, Small-signal ac modeling, and analysis of various DC to DC converters.			
Module 2		12 hours	
Single ended primary inductance converter, interleaved converters, PWM building blocks, Various control techniques, PWM control of DC-DC converter, Stabilization.			
Module 3		8 hours	
Zero current switching DC-DC converters, Zero Voltage switching DC-DC converter, ZVS converter, flyback converter, resonant converters, PWM for Class D audio amplifier.			

Voltage references, Temperature and power supply sensitivity, Analysis of negative feedback circuits, voltage regulators.

Applications emphasized include dc-dc converters for computer power and portable applications, dc-ac inverters for gas discharge lighting ballasts and wireless power transfer, LED drivers and solar micro-inverters.

Reference Books

Module 4

Subject Code

- 1. Gabriel Rincon-Mora, Analog IC Design with Low Dropout Regulators, McGraw-Hill, 2009.
- 2. Marian K. Kazimierczuk, Pulse-Width Modulated DC-DC Power Converters, Wiley, 2008.
- 3. R. W. Erickson and D. Maksimovic, *Fundamentals of Power Electronics*, Kluwer, Second Edition, 2001.

Credits: 3(3-0-0)

10 hours

Subject Code EC812	Advanced Topics in VLSI	Credits: 3(3-0-0) Total hours: 42
LC012		Total Hours. 12
Course Objectives	This course covers the advanced topics in the VLSI Design and emphasis will be given to one specific domain of integrated circuit design. Most often, this will address an application space that has become particularly relevant in recent times. Examples are serial links, ultra-low-power design, wireless transceiver design.	
Module 1		21 hours
Topics on Wireless transceiver design, Sensor design, Wireless body area networks, RF ID		
Module 2		21 hours
Topics on Ultra low power design, Serial links etc.		

References

- 1. Journal of Solid-State Circuits (JSSC)

- Transactions of Circuits and Systems I (TCAS-I)
 Transactions of Circuits and Systems II (TCAS-II)
 Transactions on Very Large Scale Integration Systems (TVLSI)
- 5. IEEE Journal on Emerging and Selected Topics in Circuits and Systems
- 6. Other relevant Journal and conference papers

Subject Code	M	Credits: 3(3-0-0)
EC813	Memory Design & Testing	Total hours: 42
Course Objectives	This course covers the analysis, design and testing of Memory basic building blocks. Memory technologies like DRAM, interfacing circuits are covered.	· ·
Module 1		12 hours
Review of CMOS circuit design, architectures, Open and folded arrays, sensing basics, refresh, kickback, SRAM		

Review of CMOS circuit design, architectures, Open and folded arrays, sensing basics, refresh, kickback, SRAM (Read and Write operation, 6T, 8T cell implementation etc.), floating-gate architectures, sense amplifiers, Sensing using Sigma-Delta Modulation.

Module 2 12 hours

Introduction to DRAM, High speed DRAM architectures, bandwidth, latency, and cycle time, Power, Timing circuits, Control logic, FLASH (FLASH array sensing and programming), Charge Pump, PROM, EPROM

Module 3 10 hours

RAM Fault Modeling, RAM Electrical Testing, RAM Pseudorandom Testing, Megabit DRAM Testing, IDDQ Fault Modeling and Testing, Application Specific Memory Testing.

General Design for Testability Techniques, RAM Built-in Self-Test (BIST), Embedded Memory DFT and BIST Techniques, Advanced BIST and Built-in Self-Repair Architectures. DFT and BIST for ROMs, Memory Error-Detection and Correction Techniques, Memory Fault-Tolerance Designs.

Module 4 8 hours

Reliabilities issues, Topics in Advanced Memory Technology, Application Specific Memories and Architectures, High Density memory package Technologies.

- 1. Betty Prince, Semiconductor Memories: A Handbook of Design, Manufacture and Application, Wiley, Second Edition, 1996.
- 2. Keeth, Baker, Johnson, and Lin, *DRAM Circuit Design: Fundamental and High-Speed Topics*, Wiley-IEEE, 2007.
- 3. Jacob Baker, CMOS Circuit Design, Layout, and Simulation, Wiley-IEEE, Third Edition, 2010.
- 4. Ashok K. Sharma, Semiconductor Memories: Technology, Testing, and Reliability, Wiley-IEEE, 2013.

Subject Code	IC for Broadband communication	Credits: 3(3-0-0)
EC814		Total hours: 42
Course Objectives	The objective of this course is to study digital signal transmi	ssion over lossy and
	dispersive channels, equalization, IC broadband amplifiers, feed-	forward and decision
	feedback equalization, clock and data recovery circuits. It provide	es an understanding of
	signal degradation, techniques to combat them, and integrated circ	cuit implementation of
	these techniques.	
Module 1	Digital signal transmission	12 hours
Digital signal transmis	ssion over lossy and dispersive channels: Eye diagrams; Eye closure	; crosstalk, and jitter;
Synchronization: clock and data recovery circuits using phase locked loops and delay locked loops,		

Module 2	Equalization	12 hours
Equalization: Transmit pre	Le-emphasis, Receive feed-forward equalization, and decision feedba	l ck equalization.
Module 3	IC broadband amplifiers for transmitter and receiver	10 hours
	-	
Integrated circuit implementation of broadband amplifiers for transmission and reception, feed-forward and		
decision feedback equalization.		
Module 4	Clock and data recovery circuits	8 hours

Clock and data recovery circuits, multiplexers, and demultiplexers.

- 1. David Johns and Ken Martin, Analog Integrated Circuit Design, John Wiley & Sons, 1997.
- 2. Y. Tsividis, *Mixed Analog Digital VLSI Devices and Technology (An introduction)*, World Scientific, 2002.
- 3. Gray, Hurst, Lewis, and Meyer, *Analysis and design of Analog Integrated Circuits*, John Wiley and Sons, Fifth Edition, 2009.
- 4. K. R. Laker and W.M.C. Sansen, *Design of Analog Integrated Circuits and Systems*, McGraw-Hill, 1994
- 5. Behzad Razavi, Design of Analog CMOS Integrated Circuits, McGraw-Hill, 2000.

Subject Code EC815	CMOS RF IC Design	Credits: 3 (3-0-0) Total hours: 42
Course Objectives	The objective of this course is to cover the circuit design	
Ů	implementation techniques at RF frequencies specific to CMOS technologies.	
Module 1	Historical Aspects	8 hours

Historical Aspects — From Maxwell to current wireless standards, The bridge between communication system designer and RF IC designer, common system characterization, RF system characterization.

Module 2 Transceiver Architectures 8 hours

Transceiver Architectures — motivation for the individual blocks, lumped, passive RLC, RF properties of MOS, Tuned amplifiers.

Module 3 Low Noise Amplifier and mixer 14 hours

Noise sources, cascades, Low Noise Amplifier — design examples, Mixers — Introduction, active and passive.

Module 4 Oscillators & synthesizers 12 hours

Analysis fundamentals and inductors, LC oscillators and VCOs, Frequency Synthesizers: Principles, design, Integer N vs. Fractional PLL.

- 1. T. H. Lee, *The Design of Radio-Frequency Integrated Circuits*, Cambridge University Press, 2004.
- 2. B. Leunge, VLSI for Wireless Communication, Personal Education Electronics and VLSI series, Pearson Education, 2002.
- 3. B. Razavi, RF Microelectronics, Prentice Hall, 1998.

Subject Code EC816	Advanced Antenna Theory	Credits: 3(3-0-0) Total hours: 42
Course Objectives	The main objective is to study modern antenna concepts for various applications. The course will explain basic antenna parameters, different types of antenna and array configurations. The concepts can further be extended in the VLSI domain for RF IC design.	
Module 1	Fundamental Concepts	10 hours
Dhysical concept of rad	lation Padiation nattern near and for field regions reciprocity	directivity and gain

Physical concept of radiation, Radiation pattern, near-and far-field regions, reciprocity, directivity and gain, effective aperture, polarization, input impedance, efficiency.

Module 2 Radiation from Wires and Loops. 10 hours

Infinitesimal dipole, finite-length dipole, linear elements near conductors, dipoles for mobile communication, small circular loop.

Module 3Aperture, Reflector and Broadband Antennas.12 hours

Huygens' principle, radiation from rectangular and circular apertures, radiation from sectoral and pyramidal horns, prime-focus parabolic reflector antennas, Log-periodic and Yagi antennas, frequency independent antennas, broadcast antennas.

Module 4 Microstrip Antennas and Antenna Arrays 10 hours

Basic characteristics of microstrip antennas, feeding methods, methods of analysis, design of rectangular and circular patch antennas, Analysis of uniformly spaced arrays with uniform and non-uniform excitation amplitudes.

- 1. C. A. Balanis, Antenna Theory and Design, John Wiley & Sons, Third Edition, 2005.
- 2. W. L. Stutzman, and G. A. Thiele, *Antenna Theory and Design*, John Wiley & Sons, Second Edition, 1998.
- 3. R. S. Elliot, Antenna Theory and Design, Wiley-IEEE Press, Revised Edition, 2003.

Subject Code EC817	VLSI Signal Processing	Credits: 3(3-0-0) Total hours: 42
Course Objectives	This course covers the various VLSI architectures and algorithms for digital signal processing. This course describes the basic ideas about digital signal processing. This course also describes the techniques of critical path and algorithmic strength reduction in the filter structures.	
Module 1	DSP Concepts	12 hours

Linear system theory, DFT, FFT, realization of digital filters. Typical DSP algorithms, DSP applications. Data flow graph representation of DSP algorithm.

Module 2 Architectural Issues 10 hours

Binary Adders, Binary multipliers, Multiply Accumulator (MAC) and Sum of Product (SOP). Pipelining and Parallel Processing, Retiming, Unfolding, Folding and Systolic architecture design.

Module 3Fast Convolution10 hours

Cook-Toom algorithm, modified Cook-Toom algorithm, Winograd algorithm, modified Winograd algorithm, Algorithmic strength reduction in filters and transforms, DCT and inverse DCT, parallel FIR filters.

Module 4 Power Analysis in DSP systems 10 hours

Scaling versus power consumption, power analysis, power reduction techniques, power estimation techniques, low power IIR filter design, Low power CMOS lattice IIR filter.

- 1. Keshap K. Parhi, VLSI Digital Signal Processing Systems, Design and Implementation, John Wiley, 2007.
- 2. U. Meyer-Baese, Digital Signal processing with Field Programmable Arrays, Springer, 2007.
- 3. V. K. Madisetti, VLSI Digital Signal Processors: An Introduction to Rapid Prototyping and Design Synthesis, IEEE Press, New York, 1995.
- 4. S. Y. Kung, H. J. Whitehouse, VLSI and Modern Signal Processing, Prentice Hall, 1985.

Subject Code EC818	Multi-rate Signal Processing	Credits: 3(3-0-0) Total hours: 42	
Course Objectives	This course covers the basic ideas about decimator, interpolator, multi-rate filter design and DFT filter banks. This course also describes the design of filter bank and efficient implementation of the filter banks.		
Module 1	Introduction	10 hours	

Introduction, Sampling and Signal Reconstruction, Sampling rate conversion, Decimation by an integer factor, Interpolation by an integer factor, Sampling rate conversion by a rational factor, Sampling rate converter as a time variant system, Practical structures for decimators and interpolators.

Module 2 Multi-rate filter design 10 hours

Direct form and Polyphase FIR structures, FIR structures with time varying Coefficients, Design of FIR filters for sampling rate conversion, Multistage design of decimator and interpolator, Applications of Interpolation and decimation in signal processing.

Module 3 Maximally Decimated Filter Banks 10 hours

Introduction, errors created in QMF bank, alias free QMF system, power symmetric QMF banks, M-channel filter banks, polyphase representation, perfect reconstruction systems; Paraunitary Perfect Reconstruction (PR) Filter Banks, lossless transfer matrices, filter bank properties induced by paraunitariness, two channel FIR paraunitary QMF banks, two channel paraunitary QMF lattice, M-channel FIR paraunitary filter banks;

Module 4 Linear Phase Perfect Reconstruction QMF Banks 12 hours

Introduction, lattice structures for linear phase FIR PR QMF banks, formal synthesis of linear phase FIR PR QMF lattice; Cosine modulated Filter Banks, efficient polyphase structures, cosine modulated perfect reconstruction systems. Applications of Multirate Signal Processing: Analysis of audio, speech, image and video signals.

- 1. P. P. Vaidyanathan, Multirate Systems and Filter Banks, Pearson-Education, 2004.
- 2. N. J. Fliege N J, Multirate Digital Signal Processing, John Wiley and sons, 1994.
- 3. J. G. Proakis, & D. G. Manolakis, *Digital Signal Processing Principles, Algorithms and Applications*, Prentice Hall of India, 2002.
- 4. S. K. Mitra, Digital Signal Processing-A Computer Based Approach, Tata McGraw Hill, 2003.

Subject Code EC819	Multimedia-Systems	Credits: 3(3-0-0) Total hours: 42	
Course Objectives	The objective of the course is to learn hardware accelerators for embedded systems. The course covers basics of embedded processing systems and various algorithms for multimedia and image	es of embedded multimedia, image	
Module 1	Multimedia Application	5 hours	

An extensive overview of state-of-the-art techniques, traditional development flows and algorithms on multimedia, image and multimedia processing, audio processing and highlight their limitations in the light of performance, power, and memory requirements. Programmable and custom architectures and algorithms, advanced video memories hierarchies and specialized (multi-/many-core) hardware processor architectures and design methods (e.g., Pipelined MPSoCs, Stream Processors, and Stochastic Processors).

Module 2	Algorithms and Embedded systems	17 hours
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Review of various architecture types, design consideration, memory reuse mechanisms, sub-task scheduling, architecture evaluation, resource sharing; High performance architectures, wavelet VLSI architectures; DCT architectures; lossless coders, Advanced arithmetic architectures and design methodologies: division and square root; finite field arithmetic; cordic algorithms and architectures for fast and efficient vector-rotation implementation; advanced systolic design; low power design; power estimation approaches; system exploration for custom low power data storage and transfer; hardware description and synthesis of DSP systems.

Module 3	Architectures for multimedia CODEC module	20 hours

Design and analysis of several light-weight multimedia and image processing algorithms and computation management techniques. Study of various architectures for motion estimation, Intra prediction, Integer discrete cosine transform, motion compensation, deblocking filter, entropy coder, system integration and Future generation hardware codecs.

- 1. Richardson, Iain E, The H.264 advanced video compression standard, John Wiley & Sons, 2011.
- 2. Articles on IEEE Transactions on Circuits and Systems for Video Technology, Multimedia, VLSI Systems, consumer electronics etc.,.
- 3. Lee, Jae-Beom, and Hari Kalva. *The VC-1 and H. 264 video compression standards for broadband video services*. Vol. 32, Springer, 2008
- 4. Parhi, Keshab K., and Takao Nishitami, *Digital signal processing for multimedia systems*, CRC Press, 1999
- 5. Parhi, Keshab K, VLSI digital signal processing systems: design and implementation, John Wiley & Sons, 2007.
- 6. Tian, Xiaohua, M. Le Thinh, and Yong Lian, *Entropy Coders of the H. 264/AVC Standard*, Springer, 2011.
- 7. Lin, Youn-Long Steve, et al. VLSI Design for Video Coding, Springer, 2010.
- 8. Ramachandran, and Seetharaman, *Digital VLSI systems design*, springer, 2007.

Subject Code		Credits: 1
EC820	Selected Topics in ECE-I	Total hours: 14
Course Objectives	This course covers the current topics in the ECE and emphasis will be given to application space that has become particularly relevant in recent times.	
Syllabus can be framed	l according to the need.	

Subject Code EC821	Selected Topics in ECE-II	Credits: 2 Total hours: 28
Course Objectives	This course covers the current topics in the ECE and emphasis will be given to application space that has become particularly relevant in recent times.	
Syllabus can be framed a	ccording to the need.	

Subject Code EC822	Selected Topics in ECE-III	Credits: 3 (3-0-0) Total hours: 42	
Course Objectives	This course covers the current topics in the ECE and emphasis will be given to application space that has become particularly relevant in recent times.		
Syllabus can be framed ac	ecording to the need.		

Program Electives

Subject Code	Data Structures & Algorithms	Credits: 3 (3-0-0)
EC850	Data Structures & Angorithms	Total hours: 42
Course Objectives	Following this course, students will be able to: 1) Solve problems us as linear lists, stacks, queues, hash tables, binary trees, heaps, to search trees, and graphs and writing programs for these solutions. 2 algorithm design methods such as the greedy method, divide a programming, backtracking, branch and bound and writing programs	urnament trees, binary) Solve problems using and conquer, dynamic
Module 1	programming, backtracking, branch and bound and writing programs	4 hours
	structures and objectives, basic concepts Arrays: one dimension	
Elementary Operation		iai, muiti-aimensionai,
Module 2		6 hours
	on, elementary operations and applications such as infix to postf	
parenthesis matching,	Queues: Simple queue, circular queue, dequeue, elementary operations	s and applications.
Module 3		8 hours
manipulation.	circular and doubly linked lists, elementary operations and application	
Module 4		8 hours
•	presentation, tree traversal, complete binary tree, heap, binary search treed 2-3 tree and other operations and applications of trees.	e, height balanced
Module 5		8 hours
Graphs: Representati	on, adjacency list, graph traversal, path matrix, spanning tree; into	roduction to algorithm
analysis and design to searching, linear and	echniques, algorithms on sorting: selection sort, bubble sort, quick sort binary search.	, merge sort, heap sort,
Module 6	(Miscellaneous Topics)	10 hours
Hash tables, direct ac	ldress tables, hash tables, hash functions, open addressing, search tree	es, binary search trees,
_	y trees. B – Trees, binomial heaps, fibonacci heaps, data structures in pression, text similarity testing-range trees, priority search trees, quad to	
Reference books	1 , seeman de dese, prostej seman dees, quad	
 Alfred V 2003. Ellis Horo 	Aho, John E Hopcroft, Jeffrey D. Ullman, <i>Data structures & algorita</i> owitz, Sartaj Sahni and Dinesh Mehta, <i>Fundamentals of data structure</i> algotia Publications, Second Edition, 2006.	•
3. Michael 7	Γ. Goodrich, Roberto Tamassia, <i>Data Structures and algorithms in Jaw</i> th Edition, 2010.	va, John Wiley & Sons,

4. Thomas H. Cormen, Charles E. Leiserson, Ronald L.Rivest, Clifford Stein, Introduction to algorithms,

MIT Press, Second Edition, 2003.

Subject Code EC851	Advanced Computer Architecture	Credits: 3(3-0-0) Total hours: 42
Course Objectives	The objective of the course is to cover concepts related to parallel computer models, advanced processors, pipelining, multiprocessors, and memory hierarchy design for optimal performance of the system.	
Module 1	Parallel Computer Models	10 hours

Classification of parallel computers, multiprocessors and multicomputer, conditions of parallelism, data and resource dependencies, grain size and latency, grain packing and scheduling, program flow mechanisms, system interconnect architectures.

Module 2	Advanced Processors	12 hours

Principles of scalable performance, performance metrics and measures, superscaler and vector processors, advanced processor technology, CISC scalar processors, RISC scalar processors, superscalar processors, VLIW architectures, vector and symbolic processors.

Module 3	Pipelining and Multiprocessors	12 hours
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Linear pipeline processor, nonlinear pipeline processor, instruction pipeline design, mechanisms for instruction pipelining, dynamic instruction scheduling, branch handling techniques, branch prediction, arithmetic pipeline design, multifunctional arithmetic pipelines, Multiprocessors and multi computers, multiprocessor system interconnects, cache coherence and synchronization mechanisms, message passing schemes.

Module 4	Memory Hierarchy Design	8 hours
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Cache basics & cache performance, reducing miss rate and miss penalty, multilevel cache hierarchies, main memory organizations, design of memory hierarchies.

- 1. K. Hwang, Advanced Computer Architecture, TMH, 2001.
- 2. W. Stallings, Computer Organization and Architecture, McMillan, 1990.
- 3. M. J. Quinn, Designing Efficient Algorithms for Parallel Computer, McGraw Hill, 1994.

Subject Code EC852	Optimization Techniques	Credits: 3 (3-0-0) Total hours: 42	
Course Objectives	The objective of this course is to study convex optimization techniques, non-linear programming with unconstrained and constrained optimization problems, reliability theory and dynamic programming.		
Module 1	Convex optimization techniques	12 hours	

Convex sets and functions, constrained optimization methods: Introduction, Kuhn-Tucker conditions, convex optimization, Lagrange multipliers.

Module 2 Non-linear programming 8 hours

One-dimensional minimization method, search method, unconstrained and constrained optimization theory and practices.

Module 3 Reliability 10 hours

Basic concepts, conditional failure rate function, Failure time distributions, Certain life models, Reliability of a system in terms of the reliability of its components, series system, and Parallel system.

Module 4Dynamic Programming12hours

Multistage decision problems, computation procedure and case studies. Fundamentals of queuing system, Poisson process, the birth and death process, special queuing methods.

- 1. S. S. Rao, Optimization: Theory and Practices, New Age Int. (P) Ltd. Publishers, 2009.
- 2. E. K. P. Chong, and S. H. Zak, An Introduction to Optimization, John Wiley & Sons, 2013.
- 3. A. L. Peressimi, F. E. Sullivan, J. J. Uhl, *Mathematics of Non-linear Programming*, Springer Verlag, 1993.

Subject Code	Linear Algebra	Credits: 3 (3-0-0)	
EC853		Total hours: 42	
Course Objectives	This course covers the fundamentals of linear algebra and matrices theory. It is intended as a broad course from engineering perspective. The first part covers the vector space, transformations and matrices theory and also provides the geometrical setting. The second part is intended to solve practical problems and provide algorithmic solutions.		
Module 1	Vector Space	5 hours	
	or algebra, subspaces, basis vectors, Linear Transformadeterminant, inverse, condition number;	ations and Matrices, matrix	
Module 2	Characteristic Equation	5 hours	
_	fors of matrices and eigenvalue decomposition; Hermitian and ary matrices, projection matrices and other special matrices;		
Module 3	Inner Product Space	5 hours	
Inner product spaces a	nd vector norms, Gramm-Schmidt orthonormalization; bilinear	forms;	
Module 4	Solution of Equations	5 hours	
Solution of equations:	Gaussian Elimination, pivoting, LU and Cholesky factorization	ns;	
Module 5	Orthogonolization	7 hours	
	Least Squares: Householder and Givens Matrices, QR factoriz Rank Deficient LS Problem;	ations, Full Rank Least	
Module 6	Eigen Value Problem	8 hours	
Symmetric Eigenvalue SVD, Lanczos and Arr	e Problem: power iterations, symmetric QR algorithm, Jacobi moldi methods;	nethods, tridiagonal methods,	
Module 7	Iterative Methods	7 hours	
Iterative Methods for	Linear Systems: Jacobi and Gauss-Seidel iterations, SOR meth	ods;	
	Van Loan, <i>Matrix Computations</i> , Johns Hopkins University Pr		
2. Strang, <i>Lii</i>	near Algebra and its Application, Cengage Learning, Fourth ed	ition, 2005.	

- 2. Strang, *Linear Algebra and its Application*, Cengage Learning, Fourth edition, 2005.
- 3. Horn and Johnson, *Matrix Analysis*, Cambridge University Press, 1990.
- 4. Hoffman and Kunze, *Linear Algebra*, Prentice Hall, Second Edition, 2009.

Subject Code EC854	Random Processes	Credits: 3(3-0-0) Total hours: 42	
Course Objectives	This course covers the foundations and major concepts in random processes which are required for communications and signal processing concepts.		
Module 1	Preliminaries Independence and Conditional Probability Bondon Variables of	8 hours	

Axioms of Probability, Independence and Conditional Probability, Random Variables and their Distribution, Functions of Random Variables, Expectation, Frequently used Distributions, Jointly Distributed Random Variables, Cross Moments, Conditional Densities,

Module 2 Convergence of Sequence of Random Variables 10 hours

Various types of Convergence, Cauchy Criteria for Convergence, Limit Theorems, Convex Functions and Jensen's Inequality, Chernoff Bound and Large Deviation Theory.

Module 3Random Vectors and MMSE Estimation10 hours

Basic Definitions, The Orthogonality Principle of MMSE Estimation, Gaussian Random Vectors, Linear Innovations Sequences, Discrete Time Kalman Filtering

Module 4 Random Processes 14 hours

Random Processes, Stationarity, Counting Processes and Poisson Process, Markov Process, Discrete Time Markov Chain, Continuous Time Markov Chain, Renewal Theory, Introduction to Martingales.

- 1. Bruce Hajek, An Exploration of Random Processes for Engineers, Class Notes, 2014.
- 2. Sheldon Ross, Stochastic Processes, John Wiley and Sons, 1996.
- 3. Dimitri Bertsekas, John Tsitsiklis, *Introduction to Probability*, Athena Scientific, First Edition, 2002.
- 4. A Papoulis, S. U. Pillai, *Probability, Random Variables and Stochastic Processes*, Tata McGraw-Hill, Fourth Edition, 2002.